LM25017
Sync. DC-DC
Converter

12V

15V

-8V

3.3V

EN-PWM

PWM

UCC53x0
Isolated Gate
Driver

Switching
Node

TIDA-01160

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Engineer:

Drawn By:

Number:

TID #:

Orderable:

Sheet:

Size:

Mod. Date:

Contact:

File:

Assembly Variant:

Sheet Title:

Project Title:

Designed for:

Isolated Gate Driver for IGBT/SiC

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Label Table

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<th>Label Text</th>
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<td>001</td>
<td>ChangeMe!</td>
</tr>
<tr>
<td>002</td>
<td>ChangeMe!</td>
</tr>
</tbody>
</table>

Assembly Notes:
- ZZ1 These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ2 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ3 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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